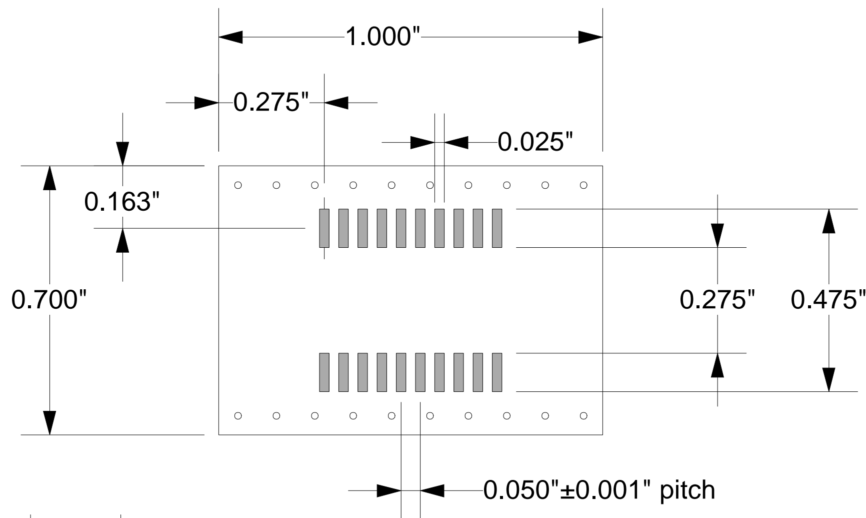
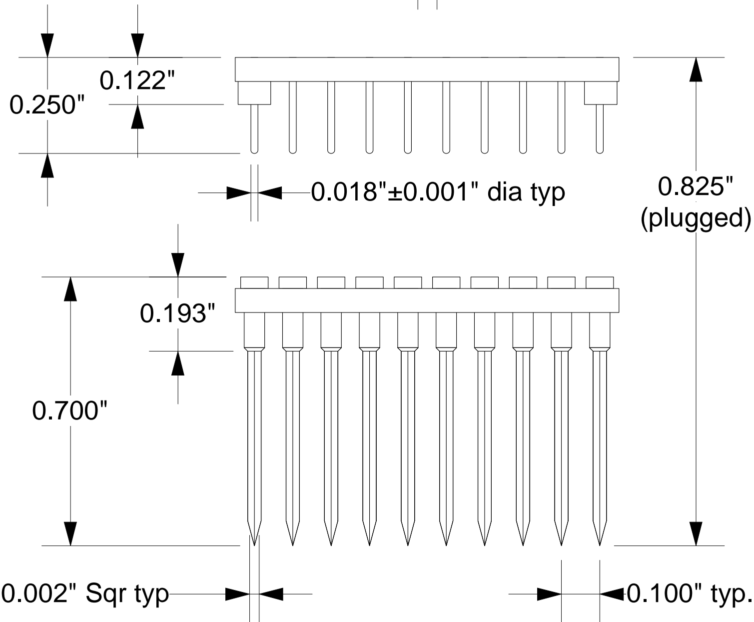
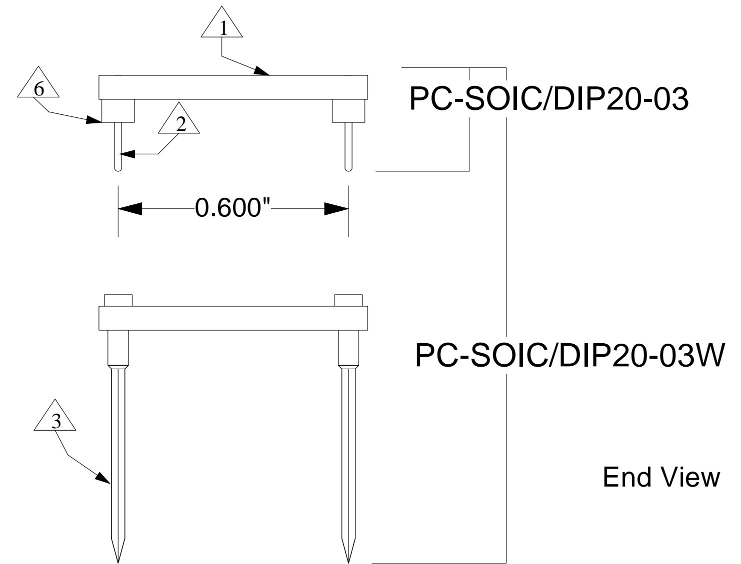


1. Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
2. Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
3. Pins: shell material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Nil (min.). Contact material- BeCu; finish 10µ" Au over 100µ" Ni (min.)
6. Stand-off: material- Teflon; 0.085" Dia; 0.060" thick.

Top View

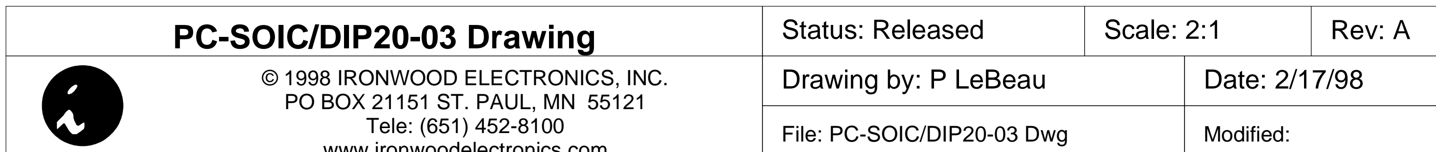




Side View

End View

Description: PACKAGE CONVERTOR
20 position (0.05" pitch) SOIC SM land pattern to 0.6" wide dip, round machined pins. Pin assignment; 1:1.
Add "W" to part number for optional wire wrap sub base.
Old part #PC-SOL/DIP20-01



PC-SOIC/DIP20-03 Drawing	Status: Released	Scale: 2:1	Rev: A
© 1998 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing by: P LeBeau	Date: 2/17/98	
	File: PC-SOIC/DIP20-03 Dwg	Modified:	

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.